



2. The printed wiring board according to claim 1, wherein said first plating layer is a conductive substrate.

3. The printed wiring board according to claim 1, wherein said insulating layer has flexibility.

4. A printed wiring board, comprising:

a laminate, said laminate including an insulating layer having a first surface and a second surface formed on the opposite side of said first surface and a plurality of wiring layers laminated on said first surface and said second surface of said insulating layer and inside of said insulating layer, said wiring layers being formed so as to correspond to a predetermined circuit pattern;

a via formed on said laminate, said via having one end opened on said first surface of said insulating layer and the other end closed by said wiring layer inside of said insulating layer;

a first plating layer, said first plating layer continuously covering said inner surface of said via, said wiring layer inside of said insulating layer exposed within said via and that portion of the wiring layer which is formed on said first surface and which faces one end of said via; and

a second plating layer, said second plating layer being laminated on said first plating layer and electrically connecting said wiring layer on said first

surface and said wiring layer inside of said insulating layer by cooperating with said first plating layer.

5       5. The printed wiring board according to claim 4, wherein said first plating layer is a conductive substrate.

6. The printed wiring board according to claim 4, wherein said laminate has flexibility.

7. A method of manufacturing said printed wiring board including said insulating layer having said first  
10       surface and said second surface located on the opposite side of said first surface and a plurality of wiring layers formed so as to correspond to a predetermined circuit pattern, said method comprising:

15       a first step of forming said wiring layers on said first and second surfaces of said insulating layer, respectively;

20       a second step of forming said via one end of which is opened on said first surface and the other end of which is closed by said wiring layer on said second surface;

25       a third step of covering said second surface of said insulating layer and said wiring layer formed on said second surface with a first plating resist;

      a fourth step of continuously covering said inner surface of said via, said wiring layer on said second surface exposed within said via and said wiring layer on said first surface with said first plating layer;

a fifth step of covering a region other than a portion where one end of said via is opened out of said first surface of said insulating layer as well as said wiring layer on said first surface with said second plating resist;

a sixth step of laminating said second plating layer on said first plating layer, and electrically connecting said wiring layer on said first surface and said wiring layer on said second surface by said first and second plating layers;

a seventh step of removing said first and second plating resists after an electrical connection is completed between said wiring layers; and

an eighth step of removing said first plating  
15 layer exposed on said first surface of said insulating  
layer along with the removal of said second plating  
resist.

8. The method of manufacturing a printed wiring board according to claim 7, wherein in said second step, said via is formed by irradiating a laser at a position other than said wiring layer out of said first surface of said insulating layer, and said insulating layer is scraped off in the direction from said first surface to said second surface.

25           9. The method of manufacturing a printed wiring  
board according to claim 7, wherein in said eighth  
step, said first plating layer is removed by etching.





where one end of said via out of said first surface of said insulating layer as well as said wiring layers on said first and second surfaces with said plating resist;

5           a fourth step of continuously covering said inner surface of said via, said wiring layer formed on said second surface exposed within said via and that portion of the wiring layer which is formed on said first surface of said insulating layer and which is other  
10           than said plating resist, by use of said first plating layer;

          a fifth step of laminating said second plating layer on said first plating layer and electrically connecting said wiring layer on said first surface and  
15           said wiring layer and said second surface with said first and second plating layers; and

          a sixth step of removing said plating resist after an electric connection is completed between said wiring layers.

20           12. The method of manufacturing a printed wiring board according to claim 11, wherein in said second step, said via are formed by irradiating a laser at a position other than said wiring layer out of said first surface of said insulating layer and scraps off  
25           said insulating layer in the direction from said first surface to said second surface by said laser.

13. A method of manufacturing a printed wiring

board, said method comprising:

5           a first step of obtaining said laminate having  
said insulating layer having said first surface and  
said second surface located on the opposite side of  
said first surface and a plurality of wiring layers  
laminated on said first surface and said second surface  
of said insulating layer and inside of said insulating  
layer and formed so as to correspond to a predetermined  
circuit pattern;

10           a second step of forming said via said one end  
of which is opened on said first surface of said  
insulating layer and the other end of which is closed  
by said wiring layer inside of said insulating layer on  
said laminate;

15           a third step of covering said second surface of  
said insulating layer and a region other than a portion  
where one end of said via is opened out of said first  
surface of said insulating layer as well as said wiring  
layers on said first and second surfaces with said  
20   plating resist;

          a fourth step of continuously covering said inner  
surface of said via, said wiring layer inside of said  
insulating layer exposed within said via and a portion  
other than said plating resist out of said wiring layer  
25   on said first surface of said insulating layer with  
said first plating layer;

          a fifth step of laminating said second plating



layer on said first plating layer, and electrically connecting said wiring layer on said first surface and said wiring layer inside of said insulating layer by said first and second plating layers; and

- 5           a sixth step of removing said plating resist after  
an electric connection is completed between said wiring  
layers.